



\$1762

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kumar et al.	Examiner: B. Talbot
Serial No. 09/903,114	Group Art Unit: 1762
Filed: July 11, 2001	
For: THERMAL PROCESSING SYSTEM AND METHODS FOR FORMING LOW-K DIELECTRIC FILMS SUITABLE FOR INCORPORATION INTO MICROELECTRONIC DEVICES	Docket No. FSI0006/US72

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Commissioner for Patents
Washington, D.C. 20231

I CERTIFY THAT ON WEDNESDAY, NOVEMBER 27, 2002, THIS PAPER IS BEING DEPOSITED WITH THE U.S. POSTAL SERVICE AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO THE COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.

Barbara A. Avery
BARBARA A. AVERY

RESPONSE

Dear Sir:

The following remarks and amendments are submitted in response to the Examiner's Office Action mailed June 28, 2002. Claims 1-37 are pending. With this response, claims 5, 6, and 7 are amended and claims 38-48 are cancelled. Reconsideration and further examination of the application are respectfully requested.

Request for Extension of Time

Pursuant to 37 CFR 1.136, Applicant hereby requests a two-month extension of time to respond to the Office Action mailed June 28, 2002, extending the date for response to November 28, 2002. Enclosed is a check in the amount of \$400.00 to cover the fee for the extension of time. The Commissioner is authorized to charge any additional fees or credit any overpayment to Kagan Binder Deposit Account No. 50-1775 and notify us of the same.

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